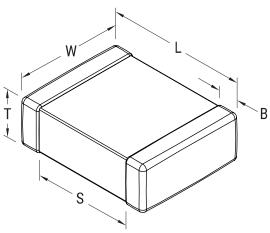




SMD Comm X8G HT150C, Ceramic, 16 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm





S Click here for the 3D model.		Termination Marking AEC-Q200	Tin No No
		Typical Component Weight Shelf Life MSL	3.7 m 78 W 1
Dimensions		Specifications	
Chip Size	0603	Capacitance	16 pF
L	1.6mm +/-0.15mm	Measurement Condition	1 MHz

VV	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm
Packaging Specifications	

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	16 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	1%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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